

98426-YXX-XX-XXXLF

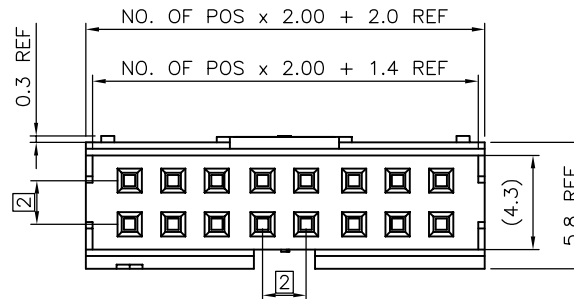
PLATING

- G : 0.76 GXT  
2µm MIN MATTE TIN ON TAIL
- S : 0.38 GXT  
2µm MIN MATTE TIN ON TAIL
- F : GOLD FLASH /2µm MIN TIN ON TAIL
- T : 2µm MIN FULL TIN  
1.27µm NICKEL MIN UNDERPLATING

LEAD FREE AND RoHS  
COMPATIBLE, NOTE 6  
BODY HEIGHT : XXX  
- MIN= 104 (10.4MM)  
- MAX= 290 (29.0MM)

PACKAGING, NOTE 3

NO. OF POS PER ROW, 03 TO 25



NOTES:

- 1 - MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC  
UL 94V-0, COLOR CREAM (SHROUD)  
AND BLACK(UNSHROUDED)
- 2 - MATERIAL TERMINAL: COPPER ALLOY
- 3 - PACKAGING  
- = STANDARD PACKAGING IN BLIBOX  
S = CUSTOM PACKAGING IN TUBE  
ONLY FOR PIN STYLE 17
- 4 - SHROUDED RETENTION FORCE 3N MIN PER POSITION
- 5 - 0.3 MAX PROTRUSION FOR -03 TO 11
- 6 - RoHS COMPATIBLE PRODUCT SPECIFICATIONS

PIN STYLE	OAL
01	12.8
02	13.5
03	14.1
04	15.6
05	16.3
06	17.1
07	18.3
08	19.1
09	20.3
10	21.1
11	22.3
12	23.3
13	26.0
14	28.0
15	30.0
16	32.0
17	11.0

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE,  
2µm MINIMUM MATTE TIN OVER 1.27µm  
MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

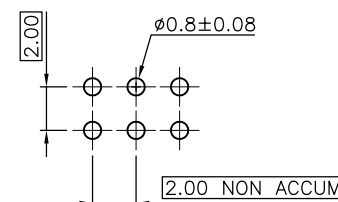
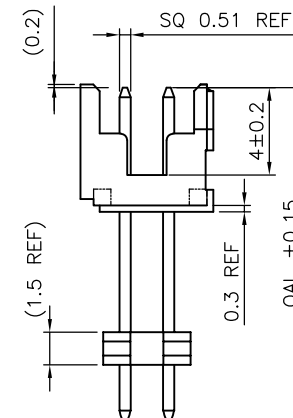
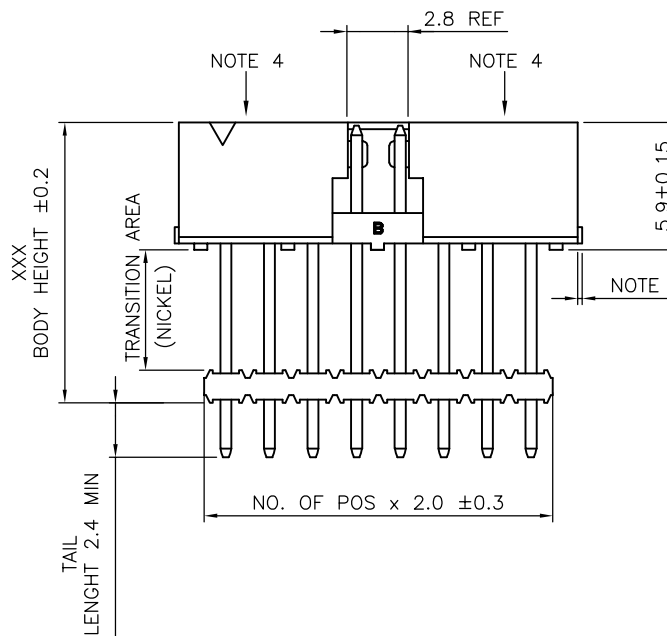
- THE HOUSING WILL WITHSTAND EXPOSURE TO  
260°C ±5°C SOLDER BATH TEMPERATURE FOR  
5 SECONDS IN A WAVE SOLDER APPLICATION  
WITH A 1.6mm MIN THICK CIRCUIT BOARD.

c - LABELING:

- MEETS PACKAGING SPECS AS PER GS-14-920

d - LEGAL STATEMENT: SEE GS-47-0004

- 6 - THIS PRODUCT IS NOT INTENDED TO BE USED THROUGH REFLOW PROCESS



RECOMMENDED HOLE PATTERN

mat'l. code		surface ISO 1302		tolerance ISO 406 ISO		projection 101		product family MINITEK	
ltr		ecn no		dr		date		title	
A		F09-0227		JCO		09.12.07		SHR STACKING HEADER MINITEK	
B		F10-0067		JCO		10.06.29		sheet 1 of 1 size	
C		B-18972		LMU		14.10.01		98426 A3	
D		B-19190		LMU		14.10.24		type	
E		B-20291		BVE		15.02.19		CUSTOMER Drawing	
F		F-27987		LMU		17.09.18			
sheet index		revision sheet							



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